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Specification for Approval

Customer:	
Model Name:	

Sı	upplier Approv	Customer approval	
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		



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Revision Record

REV NO.	REV DATE	CONTENTS	Note
Α	2012-11-13	NEW ISSUE	

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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution.

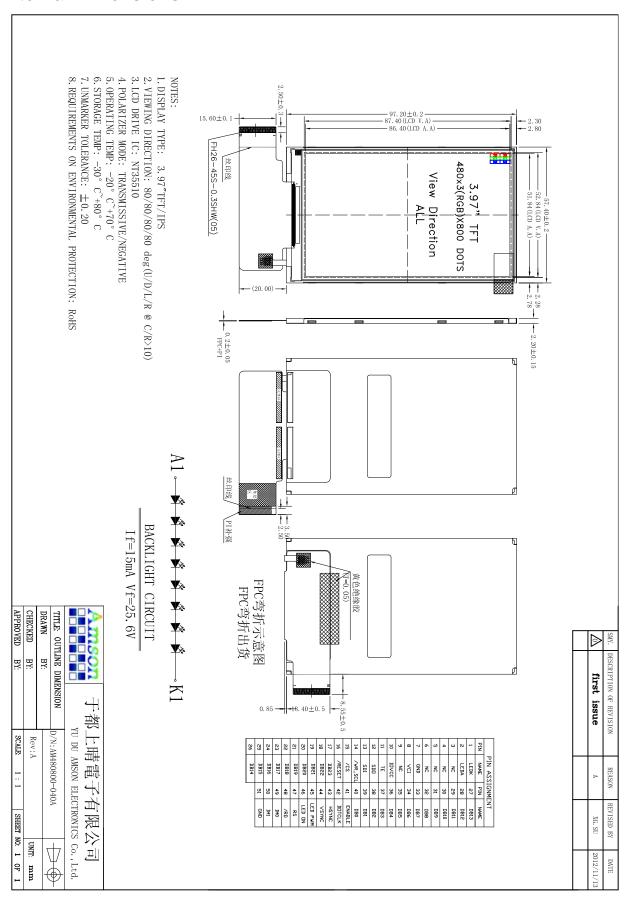
2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	4.0"TFT	
Dot arrangement	480(RGB)×800	dots
Color filter array	RGB vertical stripe	
Display mode	Transmission / Normally Black	
Viewing Direction	80/80/80/80 deg(U/D/L/R @ C/R>10)	
Driver IC	NT35510	
Module size	57.4(W)×97.2(H)×2.2(T)	mm
Active area	51.84(W)×86.40(H)	mm
Dot pitch	0.108(W)×0.108(H)	mm
Interface	8-/16-/24-bit i80-series system interface 16-/18-/24-bit RGB interface 3-line SPI interface	
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	8 White LED In Serial	
Weight	TBD	g

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3. External Dimensions





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4. Interface Description

4. 11	4. Interface Description					
Pin	Symbol	Description.				
1	LEDK	LED backlight (Cathode).				
2	LEDA	LED backlight (Anode).				
3	NC	No connection.				
4	NC	No connection.				
5	NC	No connection.				
6	NC	No connection.				
7	GND	Power ground				
8	VCC	Analog supply voltage to the analog circuit.				
9	NC	No connection.				
10	IOVCC	Logic supply voltage to the logic circuit.				
11	TE	Tearing effect output pin to synchronize MCU to frame writing.				
12	SDO	Serial output signal in SPI I/F.				
13	SDI	Serial input signal in SPI I/F.				
14	WRX(SCL)	Writes strobe signal to write data when WRX is "Low" in MPU I/F. A synchronous clock signal in SPI I/F.				
15	CSX	Chip select input pin ("Low" enable) in MPU I/F and SPI I/F.				
16	NRESET	Reset input pin, Active "L".				
17	DB23					
18	DB22					
19	DB21					
20	DB20					
21	DB19					
22	DB18					
23	DB17					
24	DB16					
25	DB15	24-bit parallel bi-directional data bus for MPU system:				
26	DB14	8-bit I/F: DB[7:0] is used. 16-bit I/F: DB[15:0] and DB[8:1] is used.				
27	DB13	24-bit I/F: DB[23:0] is used.				
28	DB12					
29	DB11	24-bit input data bus for RGB I/F.				
30	DB10	16-bit/pixel: DB[20:16]=R[4:0], DB[13:8]=G[5:0] and DB[5:1]=B[4:0];				
31	DB09	18-bit/pixel: DB[21:16]=R[5:0], DB[13:8]=G[5:0] and DB[5:0]=B[5:0];				
32	DB08	24-bit/pixel: DB[23:16]=R[7:0], DB[15:8]=G[7:0] and DB[7:0]=B[7:0]. Connect unused pins to GND.				
33	DB06					
34	DB07					
35	DB05					
36	DB04					
37	DB03					
38	DB02					
39	DB01					
40	DB00					



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	ı	
41	ENABLE	Data enable signal in RGB I/F mode
42	DOTCLK	Pixel clock signal in RGB I/F.
43	HSYNC	Horizontal sync signal in RGB I/F.
44	VSYNC	Vertical sync signal in RGB I/F.
45	LEDPWM	Connect to the external LED driver. If not used, please open this pin.
46	LEDON	Connect to the external LED driver. If not used, please open this pin.
47	DCX	Display data / command selection in 80-series MPU I/F. DCX = "0" : Command DCX = "1" : Display data or Parameter
48	RDX	Reads strobe signal to write data when RD is "Low" in MPU interface.
49	IM0	System interface Mode IM[1,0]=00, i80-system 8-bit MPU interface : DB[7:0] is used.
50	IM1	IM[1,0]=01, i80-system 16-bit MPU interface : DB[15:0] is used. IM[1,0]=10, i80-system 24-bit MPU interface : DB[24:0] is used. IM[1,0]=11, RGB+SPI interface
51	GND	Power ground

5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCC	-0.3	4.6	V
Input Voltage	Vin	-0.3	IOVCC+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

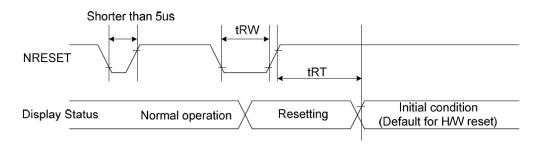
6. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	V	-
Analog Supply Voltage	VCC	2.5	2.8	3.3	V	-
Input High Voltage	V _{IH}	0.7IOVCC	-	IOVCC	V	Digital input pins
Input Low Voltage	V _{IL}	-0.3	-	0.3IOVCC	V	Digital input pins
Output High Voltage	V _{OH}	0.8IOVCC	-	IOVCC	٧	Digital output pins
Output Low Voltage	V_{OL}	0	ı	0.2IOVCC	٧	Digital output pins
I/O Leak Current	lu	-1.0	-	1.0	mA	-

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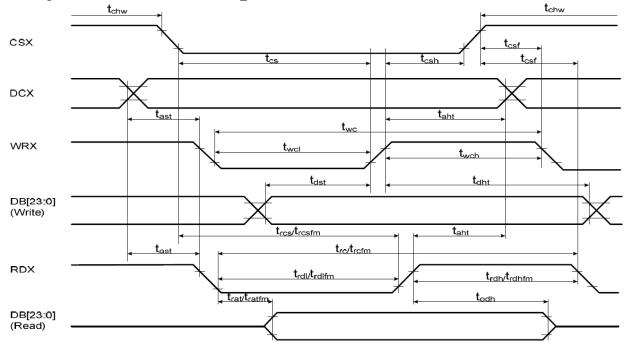
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7. Timing Characteristics7.1 Reset Timing Characteristics



Signal	Symbol	Parameter Mi		Max	Unit
	tRW Reset puls		10		us
RESX	+DT	Poset cancel		5 (note 1,5)	ms
	tRT Reset cancel			120 (note 1,6,7)	ms

7.2 i80-System Interface Timing Characteristics



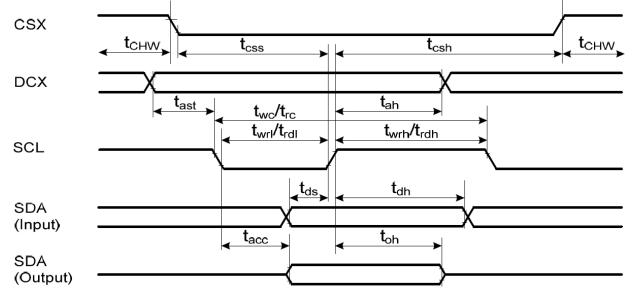


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Signal	Symbol	Parameter	min	max	Unit	Description	
DCV	tast	Address setup time	0	-	ns	-	
DCX taht		Address hold time (Write/Read)	10	-	ns	-	
	tchw	CSX "H" pulse width	0	-	ns	-	
	tcs	Chip Select setup time (Write)	10	-	ns	-	
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns	-	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	-	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	-	
	twc	Write cycle	30	-	ns	-	
WRX	twrh	Write Control pulse H duration	10	-	ns	-	
tw	twrl	Write Control pulse L duration	10	-	ns	-	
	trcfm	Read Cycle (FM)	450	-	ns	When read from the Frame	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns		
	trdlfm	Read Control L duration (FM)	355	-	ns	Memory	
	trc	Read cycle (ID)	160	-	ns		
RDX (ID)	trdh	Read Control pulse H duration	90	_	ns	When read ID data	
	trdl	Read Control pulse L duration	45	-	ns		
DD[47.0]	tdst	Write data setup time	10	-	ns		
DB[17:0], DB[15:0],	tdht	Write data hold time	10	-	ns	CL = 20nE (maximum)	
	trat	Read access time	-	40	ns	CL = 30pF (maximum) CL = 8pF (minimum)	
DB[8:0] DB[7:0]	tratfm	Read access time	-	340	ns		
<i>DD[1</i> .0]	trodh	Read output disable time	20	80	ns		

7.3 Display Serial Interface Timing Characteristics (3-line SPI system)

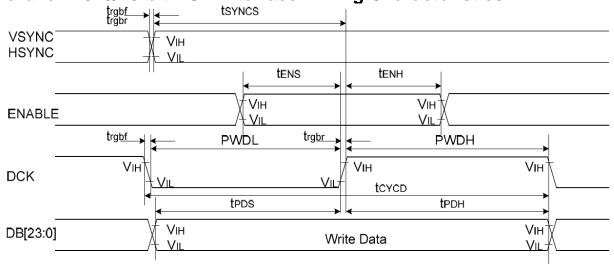


Signal	Symbol	Parameter	min	max	Unit	Description
	tcss	Chip select time (Write)	15	-	ns	
CSX	tcsh	Chip select hold time (Read)	15	-	ns	
	tchw	CS "H" pulse width	40	-	ns	
	twc	Serial clock cycle (Write)	30	-	ns	
	twrh	SCL "H" pulse width (Write)	10	-	ns	
SCL	twrl	SCL "L" pulse width (Write)	10	-	ns	
trc		Serial clock cycle (Read)	150	-	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
DCX	tas	DCX setup time	10	-	ns	
DCX	tah	DCX hold time (Write/Read)	10	-	ns	
SDA	tds	Data setup time (Write)	10	-	ns	
(Input)	tdh	Data hold time (Write)	10	-	ns	
SDA	tacc	Access time (Read)	10	50	ns	CL = 30pF (maximum)
(Output)	toh	Output disable time (Read)	15	50	ns	CL = 8pF (minimum)

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7.4 Parallel 24/18/16-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC/	VSYNC/ t _{SYNCS} VSYNC/HSYNC se		5	ı	ns	
HSYNC t _{SYNCH}		VSYNC/HSYNC hold time		-	ns	
ENABLE	t _{ENS}	ENABLE setup time	5	ı	ns	
ENABLE	t _{ENH}	ENABLE hold time		ı	ns	
DD [47:0]	t _{POS}	Data setup time		-	ns	24/18/16-bit bus RGB
DB [17:0]	t _{PDH}	Data hold time	5	-	ns	interface mode
	PWDH	DCK high-level period	13	-	ns	
DCK	PWDL	DCK low-level period		-	ns	
	t _{CYCD}	DCK cycle time		ı	ns	
	t _{rgbr} , t _{rgbf}	DCK,HSYNC,VSYNC rise/fall time	-	15	ns	

8. Backlight Characteristics

LED CIRCUIT:



Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	23.2.0	25.6	28.0	V	If=20mA
Supply Current	If		20	25	mA	
Luminous Intensity for LCM (With TP)		350	400		Cd/m ²	If=20mA
Uniformity for LCM		80	-		%	If=20mA
Life Time		50000			Hr	lf=20mA
Backlight Color				White		



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9. Optical Characteristics

Parameter		Symbol	Condition	Min.	Тур.	Max.	Unit	Remark	
Threshold Voltage		Vsat					V	F: 4	
		Vth					٧	Fig.1	
	Horiz	Θ3			85		Deg.		
Viewing	-ontal	Θ9	CD>10		85		Deg.	Note 1	
Angle	\	Θ12	CR>10		85		Deg.	Note 1	
	Vertical	Θ6			85		Deg.		
Contrast	Ratio	CR	Θ= 0°	650	900			Note 2	
								Note 3	
Transmit	tance	T(%)	Θ= 0°		5.3%			Base on	
Hallollii	Transmittance		0-0		3.5 /0			C light	
								With APF	
	Red	Rx		0.620	0.640	0.660			
Reprod-		Ry		0.315	0.335	0.355		Note 4	
uction of	Green	Gx	Θ= 0°	0.295	0.325	0.345		*Color	
color	Green	Gy] 0-0	0.576	0.606	0.626		Filter Glass	
00101	Blue	Вх		0.128	0.148	0.168		(with ITO)	
	Diue	Ву		0.025	0.045	0.065		Based on	
White		Wx	Θ= 0°	0.268	0.288	0.308		C light	
		Wy	9-0	0.299	0.319	0.339			
Response Time		Tr+Tf	Ta= 25° C Θ= 0°		35		ms	Note 5	

- Note 1. Viewing angle is the angle at which the contrast ratio is greater than 10. The viewing are determined for the horizontal or 3, 9 o'clock direction and the vertical or 6, 12 o'clock direction with respect to the optical axis which is normal to the LCD surface (see FIG.2).
- Note 2. Contrast measurements shall be made at viewing angle of Θ = 0 and at the center of the LCD surface. Luminance shall be measured with all pixels in the view field set first to white, then to the dark (black) state. (See FIG. 2) Luminance Contrast Ratio (CR) is defined mathematically. CR = White Luminance (ON) / Black Luminance (OFF)
- Note 3. Transmittance is the value with DBEF Polarizer.
- Note 4. The color chromaticity coordinates specified in Table1 shall be calculated from the spectral data measured with all pixels first in red, green, blue and white.

 Measurements shall be made at the center of the C/F. Measurement condition is C light source & Halogen Lamp
- Note 5. The electro-optical response time measurements shall be made as FIG.3 by switching the "data" input signal ON and OFF. The times needed for the luminance to change from 10% to 90% is Tr , and 90% to 10% is Tf.

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Fig.1 The definition of Vth & Vsat

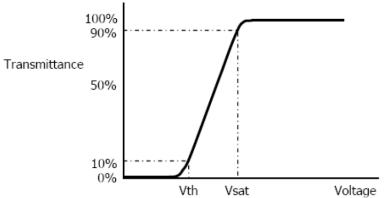


Fig.2 Measurement Set Up

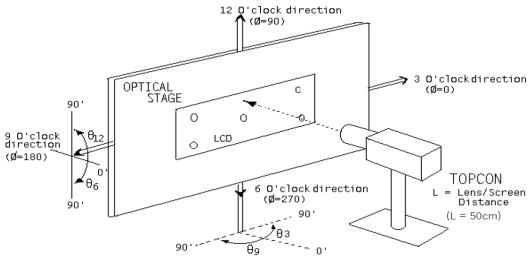
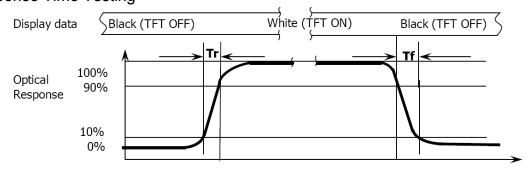


Fig.3 Response Time Testing





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10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
	High Temperature Storage	80°C±2°C×200Hours	
	Low Temperature Storage	-30°C±2°C×200Hours	
	High Temperature Operating	70°C±2°C×120Hours	Inspection after 2~4hours storage at room temperature,
	Low Temperature Operating	-20°C±2°C×120Hours	the samples should be free from defects: 1, Air bubble in the
	Temperature Cycle(Storage)	$ \begin{array}{c} -20^{\circ}\text{C} & \Longrightarrow 25^{\circ}\text{C} & \Longrightarrow 70^{\circ}\text{C} \\ (30\text{min}) & (5\text{min}) & (30\text{min}) \\ \hline & 1\text{cycle} \\ & \text{Total 10cycle} \end{array} $	LCD. 2, Seal leak. 3, Non-display. 4, Missing segments. 5, Glass crack.
	Damp Proof Test (Storage)	50°C±5°C×90%RH×120Hours	6, Current IDD is twice higher than initial value.
	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	7, The surface shall be free from damage. 8, The electric characteristic requirements shall be
	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	satisfied.
	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

- 1, The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test, Pure water(Resistance $> 10M\Omega$)should be used.
- 4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



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11. Inspection Standard

This standard apply to C-STN/TFT module

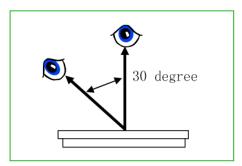
1. Spot check plan:

According to spot check level ${
m II}$,MIL-STD-105D Level ${
m II}$,the rank of accept or reject is below:

3A、2A: major non-conformance: AQL 0.25 minor non-conformance: AQL 0.4

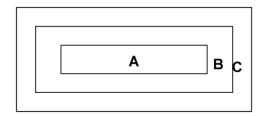
1A: major non-conformance: AQL 0.65 minor non-conformance: AQL 1.

2. Inspection condition:



Under daylight lamp 20 \sim 40W, product distance inspector 'eye 30cm,incline degree 30° $_{\circ}$

3. LCD area define:



Area A: display area

Area B: VA area

Area C: out of VA area, not in sight after assembly

Remark: non-conformance at area C, but is OK that isn't influence reliability of product & assembly by customer.



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4. Inspection standard

4.1 Major non-conformance

NO.	Item	Inspection standard	Rate
4.1.1	Function non-conformance	 No display, display abnormally Miss line, short B/L no function or function abnormally TP no function 	major
4.1.2	miss	No matter miss what component	
4.1.3	Out of size	Module dimension out of spec	

4.2 Appearance non-conformance

NO.	Item			Inspe	ection s	tanda	rd		Rate
		dot non-conformance define Φ $\Phi = \frac{+y}{2} x ($							
		A grade			••		- 14	$\overline{}$	
	Black or	area size (mm)		Most approve q'ty A B		c q'ty			
4.2.1	white spot (power	Ф≤0.1	0		ignore				Minor
	on)	0.10<Φ≤	0.15		4				
		0.15<Φ≤0.20			2 igno		ignore	e	
		0.20<Φ≤0.25		1					
		0.25<Ф			0				
		Most approve 4 damages, dot to dot ≥10mm A grade							
		Size(mm)			Most approve q'ty				1
		L(length)	W(width)		Α		В	С	
		ignore	W≤	0.03	i	ignore	,		
4.2.2	Black or white line (power on)	L≤5.0	0.03< W≤0.05		3				Minor
		L≤3.0	0.05< W≤0.07		2			ignore	
			0.07	′ <w< td=""><td colspan="2">Treat with dot non-conformance</td><td></td><td></td><td></td></w<>	Treat with dot non-conformance				
		Most approve 3 damages, line to line ≥10mm							



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4.2.3	Polarizer position	'			allow out of LC area (special		Minor		
4.2.4	LCD non-conform ance	(iii) commo	z ∫ X ≤3.0	Y <frame edge<="" th=""/> <th>Z ignore</th> <th></th> <th>Minor</th>	Z ignore		Minor		
4.2.5	Contrast voltage warp	VOP/Vlcd v	VOP/VIcd voltage of confirmed sample ± 0.15V						
4.2.6	color	Color & lun	ninance of r	nodule scope r	eference spec		Minor		
4.2.7	Cross talk	Reference	confirmed li	imit sample			Minor		



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12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Sulfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to VDD or GND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - Usage under the maximum operating temperature, 50%Rh or less is required.



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12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen this is not specified in this specification.
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

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14. Packing Method

